Preferred Device

High Voltage Transistor

PNP Silicon

Features

• Pb-Free Package May be Available. The G-Suffix Denotes a Pb-Free Lead Finish

MAXIMUM RATINGS

Rating	Symbol	MMBTA92	Unit
Collector - Emitter Voltage	V_{CEO}	-300	Vdc
Collector - Base Voltage	V_{CBO}	-300	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current - Continuous	I _C	-500	mAdc

THERMAL CHARACTERISTICS

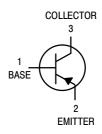
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T _A = 25°C	P _D	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C	P_{D}	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

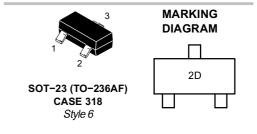
- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



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2D = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBTA92LT1	SOT-23	3000 / Tape & Reel
MMBTA92LT1G	SOT-23	3000 / Tape & Reel
MMBTA92LT3	SOT-23	10000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Voltage (Note 3) (I _C = -1.0 mAdc, I _B = 0)	V _(BR) CEO	-300	-	Vdc
Collector-Base Breakdown Voltage ($I_C = -100 \mu Adc$, $I_E = 0$)	V _(BR) CBO	-300	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = -100 \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	-5.0	-	Vdc
Collector Cutoff Current (V _{CB} = -200 Vdc, I _E = 0)	Ісво	_	-0.25	μAdc
Emitter Cutoff Current (V _{EB} = -3.0 Vdc, I _C = 0)	I _{EBO}	-	-0.1	μAdc
ON CHARACTERISTICS (Note 3)				
DC Current Gain ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$) ($I_C = -10 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$) ($I_C = -30 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$)	h _{FE}	25 40 25	- - -	-
Collector-Emitter Saturation Voltage (I _C = -20 mAdc, I _B = -2.0 mAdc)	V _{CE(sat)}	-	-0.5	Vdc
Base-Emitter Saturation Voltage (I _C = -20 mAdc, I _B = -2.0 mAdc)	V _{BE(sat)}	-	-0.9	Vdc
SMALL-SIGNAL CHARACTERISTICS	-			
Current – Gain – Bandwidth Product (I _C = -10 mAdc, V _{CE} = -20 Vdc, f = 100 MHz)	f _T	50	-	MHz
Collector–Base Capacitance (V _{CB} = -20 Vdc, I _E = 0, f = 1.0 MHz)	C _{cb}	-	6.0	pF

^{3.} Pulse Test: Pulse Width \leq 300 $\mu\text{s},$ Duty Cycle \leq 2.0%.

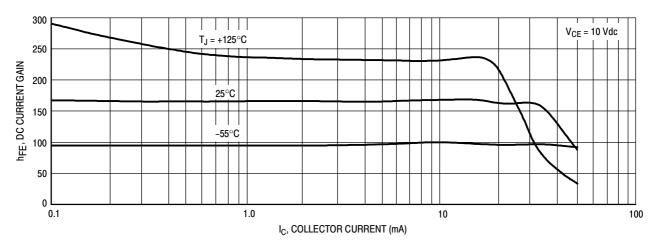


Figure 1. DC Current Gain

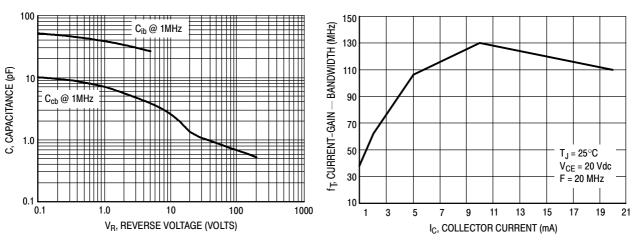
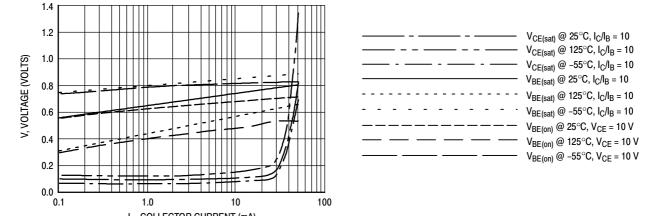


Figure 2. Capacitance



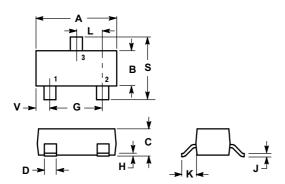
100

Figure 3. Current-Gain - Bandwidth

I_C, COLLECTOR CURRENT (mA) Figure 4. "ON" Voltages

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AH**



NOTES

- OTES.

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE
- MATERIAL.
 4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INC	CHES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.1102	0.1197	2.80	3.04	
В	0.0472	0.0551	1.20	1.40	
С	0.0350	0.0440	0.89	1.11	
D	0.0150	0.0200	0.37	0.50	
G	0.0701	0.0807	1.78	2.04	
Н	0.0005	0.0040	0.013	0.100	
J	0.0034	0.0070	0.085	0.177	
K	0.0140	0.0285	0.35	0.69	
L	0.0350	0.0401	0.89	1.02	
S	0.0830	0.1039	2.10	2.64	
v	0.0177	0.0236	0.45	0.60	

STYLE 6: PIN 1 BASE

2. EMITTER

COLLECTOR 3.

SOLDERING FOOTPRINT*

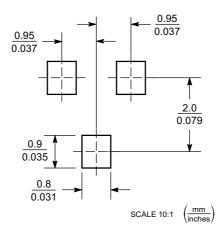


Figure 5. SOT-23

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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